

CLAIMS:

1. A method for patterning a device layer using a patterned elastomer, comprising the steps of:

- (1) providing a substrate;
- (2) bringing the patterned elastomer into contact with the substrate;
- (3) removing the patterned elastomer from the substrate;

characterised in that step (2) is carried out under conditions and for a sufficient time so that the surface energy of the substrate is modified in accordance with the pattern; and that the method further comprises a step;

- (4) depositing a device layer on the substrate after the patterned elastomer has been removed; whereby the surface energy of the substrate determines the deposition pattern of the device layer.

10. A method according to any one of claims 1 to 6, wherein the patterned elastomer is used as a mask in step (2) and step (2) includes subjecting any portion of the surface of the substrate that is not in contact with the patterned elastomer to a surface energy modifying process.

11 A method according to claim 10 wherein the surface energy modifying process includes a step of exposing any portion of the surface of the substrate that is not in contact with the patterned elastomer to UV radiation.

Fig. 7 missing